



TECHNICAL DATA SHEET

SK2TM152-1

Adhesive for epoxy boards

► DESCRIPTION

SK2TM152-1 is a fast curing and very high heat resistance adhesive for bonding of epoxy boards. This adhesive is suitable for bonding modelling boards SK2TM140-1 and SK2TM145-1 before mechanical treatment.

► PROPERTIES

- very high heat resistance
- fast curing

► APPLICATION

- bonding of epoxy boards

► PHYSICAL PROPERTIES

PRODUCT	MIXTURE	RESIN	HARDENER
Mixing ratio by weight		100	14
Viscosity at 25°C (mPas)	1800 ± 200	3800 ± 350	70 ± 15
Density at 20°C (g/cm ³)	1,13 ± 0,03	1,15 ± 0,03	0,99 ± 0,03
Pot life 150 g / 20°C (min)	30 - 35	-	-
Curing time at RT (hrs.)	16	-	-
Color	yellowish transparent	yellowish transparent	yellowish transparent

► PROCESSING INSTRUCTIONS

Mix not more than 1000g resin with 140g hardener, mixing ratio is 100:14.

The material should be processed within 10 minutes. Apply 250-300 g of adhesive with a notched spatula on both panel sides which have to be glued together. For gluing two boards together you need 500-600g of adhesive. After gluing, the blocks have to be kept at room temperature for 12-16 hours. To cure the adhesive, gently heat up the glued blocks at about 5°C/ hour and keep them at least 80 °C for 10 hours. For higher processing temperatures accordingly, give a higher heat treatment. Keep the block one more hour at the highest temperature for every 100 mm thickness.



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HEAT TREATMENT	HEAT RESISTANCE (HDT B IN °C)
8 hours at 80°C	108°C HDT B
8 hours at 100°C	123°C HDT B
8 hours at 120°C	141°C HDT B
8 Hours at 140°C	150°C HDT B

After cooling down at a rate of 5°C/ hour the block should remain at the autoclave with closed doors overnight, till it reaches room temperature also in the core. Use the same procedure for curing prepregs on the mould. When taking the block out of the autoclave don't lay it on a cold surface. An isolating layer may be placed in between.

Depending on the geometry of the tool different parameters may be necessary. For mixing and application of the material, clean and dry tools are essential. Mix according to mixing ratio. Mix carefully and apply immediately. Material temperature when mixing not below 15°C.

► PHYSICAL PROPERTIES

CHARACTERISTICS	INSPECTION REQUIREMENT	VALUE	UNIT
Flexural strength	EN ISO 178	115 ± 15	MPa
Flexural modulus	EN ISO 178	3275 ± 325	MPa
Tensile strength	EN ISO 527-1	85 ± 10	MPa
Tensile modulus	EN ISO 527-1	3215 ± 300	MPa
Elongation of tensile strength	EN ISO 527-1	3,7 ± 0,2	%
Compressive strength	EN ISO 604	125 ± 15	MPa
Heat resistance (HDT)	DIN EN ISO 75 B	152 ± 5	°C
Glass transition temperature TG	method DSC	ca. 154	°C
Shore hardness	DIN ISO 7619-1	88 ± 3	Shore D



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► PACKAGING

RESIN	HARDENER
0,877 kg	0,123 kg
4,336 kg	0,614 kg

► STORAGE

Storage at room temperature 18-25 °C. Already opened containers should be closed immediately after use and should be used as soon as possible.

You can find the information about the expiration date on the sales packages.